

METHOD AND APPARATUS FOR DECOUPLING CONDUCTIVE PORTIONS OF A  
MICROELECTRONIC DEVICE PACKAGE

ABSTRACT

A method and apparatus for decoupling conductive portions of a microelectronic device package. In one embodiment, the package can include a microelectronic substrate and a conductive member positioned at least proximate to the microelectronic substrate. The conductive member can have first and second neighboring conductive portions with at least a part of the first conductive portions spaced apart from a part of the neighboring second conductive portion to define an intermediate region between the first and second conductive portions. Each conductive portion has a bond region electrically coupled to the microelectronic substrate. A dielectric material is positioned adjacent to the first and second conductive portions in the intermediate region and has a dielectric constant of less than about 3.5.

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